

# Power Supply Theory and Practice

## 4190.309

### 2008 Fall Semester

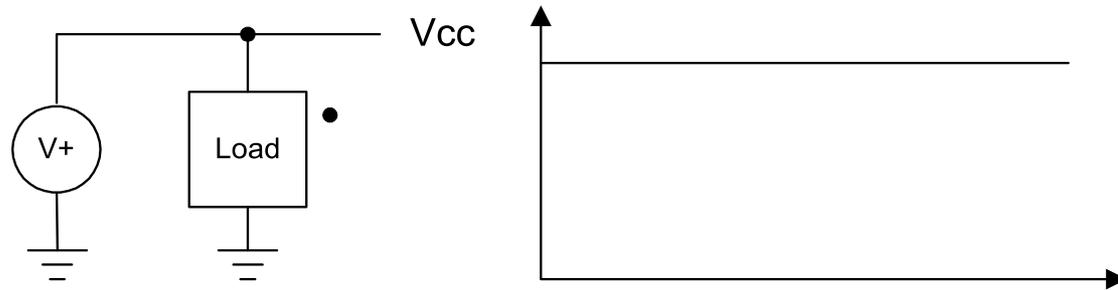
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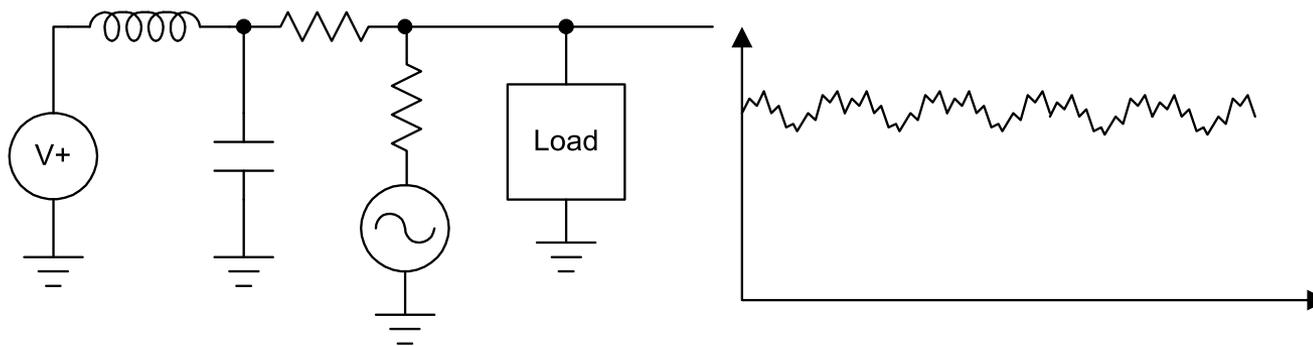
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# Ideal versus real-world power supply

- Why real power supplies are noisy?



a) Ideal power source: zero line impedance



b) Realistic power source: non-zero line impedance



# Good power supply

- Minimize power supply impedance
  - as much as possible.
- Power supply impedance
  - Resistive component
  - Inductive component

$$V_{drop} = iR + L \frac{di}{dt}$$



## Voltage drop:

$$V_{drop} = iR + L \frac{di}{dt}$$

- 20A current with DC resistance  $0.05\Omega$ 
  - yields 1V droop.
  - TTL operating range is 4.75V to 5.25V
- 0.1A current change in 2ns with 500nH
  - yields 25V drop!
  - In practice, yields much less voltage drop since 500nH prevents 0.1A current change itself in 2ns.



# Reducing DC resistance

- Use low resistance materials: copper
- Use thick wire
- Reduce contact resistance
- Internal impedance (resistance) of a power supply is also important.



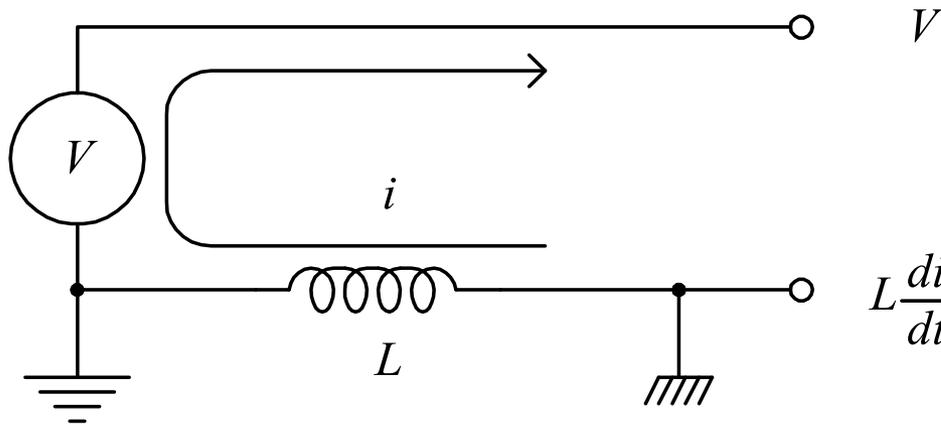
# Reducing inductance

- Use short wire.
- Make no bend or loop if possible.
- VCC is as important as GND.
- Use bypass capacitors.
- Wire thickness is not so important!
- If somebody fails in reducing inductance, he or she may suffer from ground bounce.



# Ground bounce

- Earthquake!

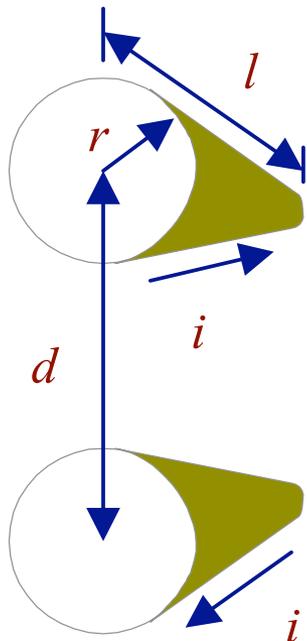


$$\leftarrow v = V - L \frac{di}{dt}$$



# Low inductance

- Short wire, no bend or loop

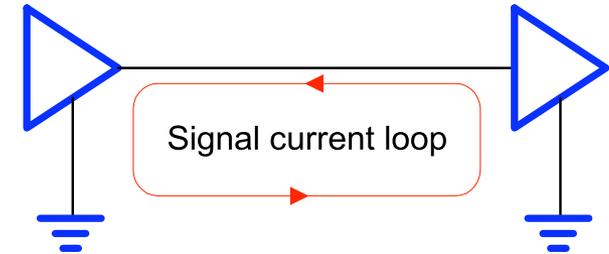
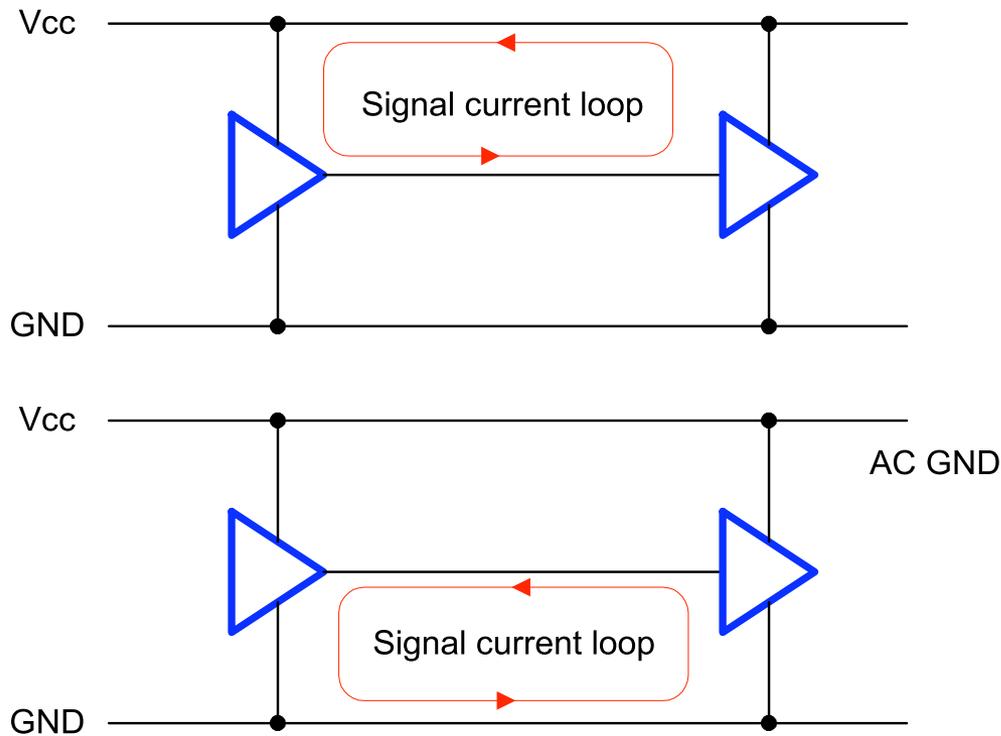


$$L = Kl \ln \frac{d - r}{r}$$



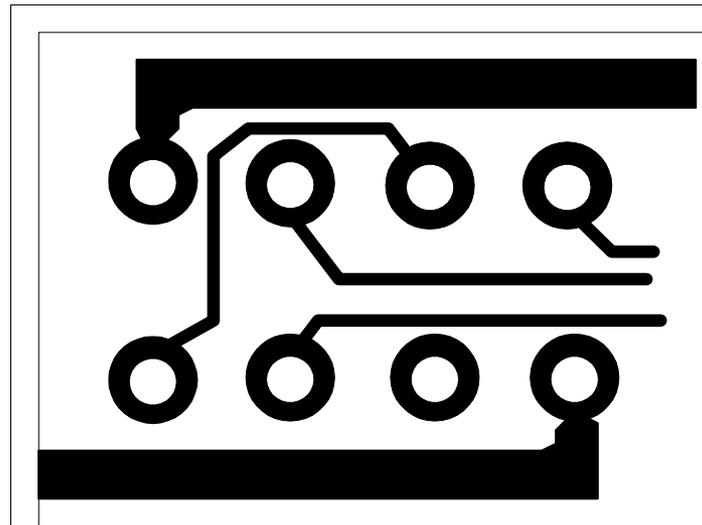
# Signal return path

- VCC and GND are signal return paths!

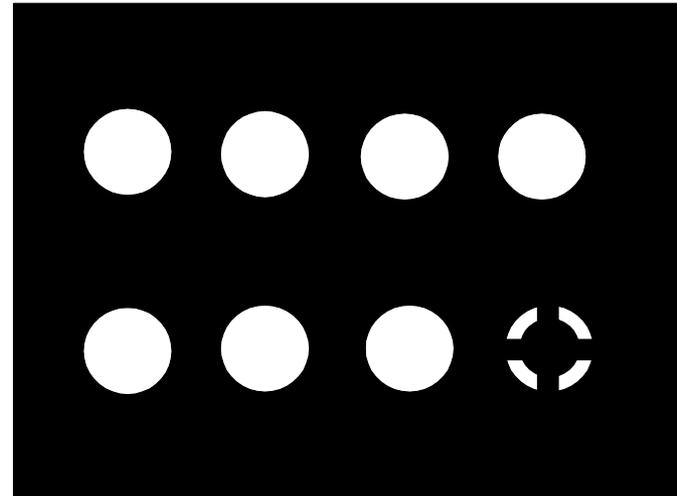


# Minimize signal return path

- Power bus and power plane



Power Bus



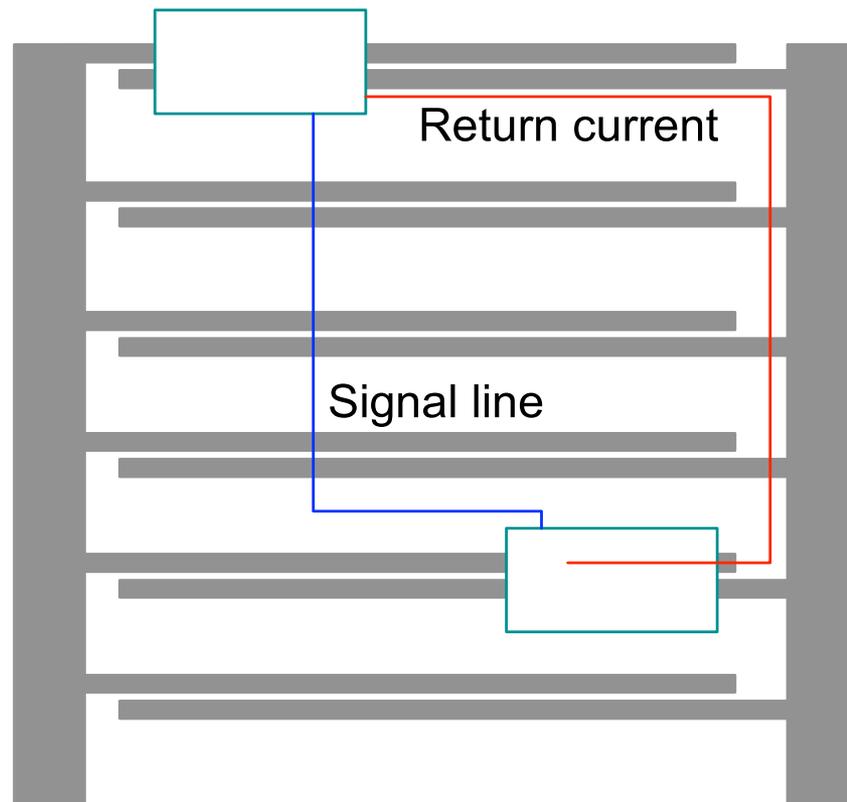
Power plane



# Power bus

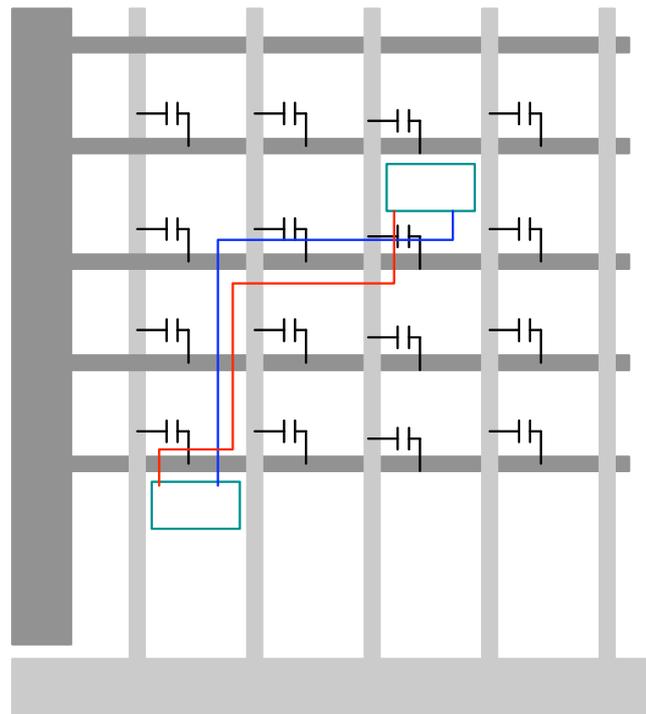
- VCC and GND fingers layout
- Track width?

$$L = Kl \ln \frac{d - r}{r}$$



# Power bus (2)

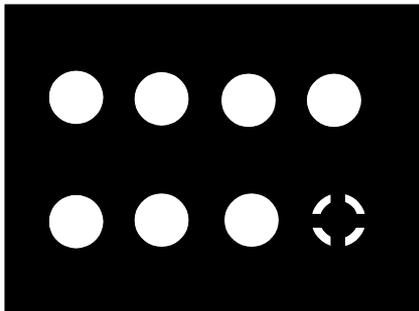
- VCC and GND grid on two layers



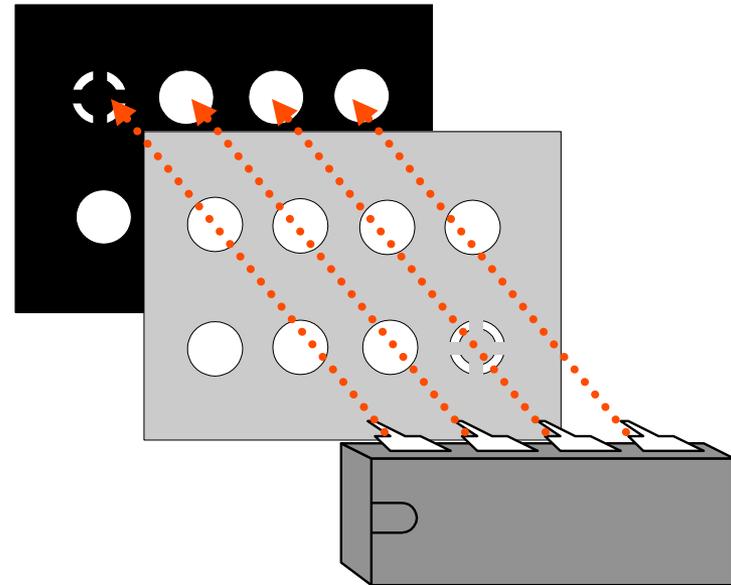
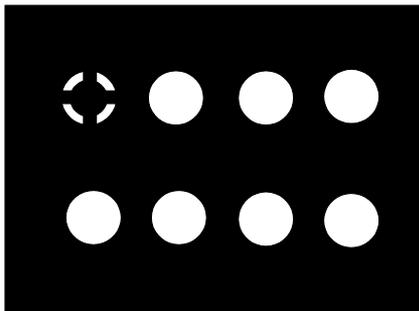
# Solid power planes

- VCC and GND planes
- Ideal for signal return path

VCC Plane

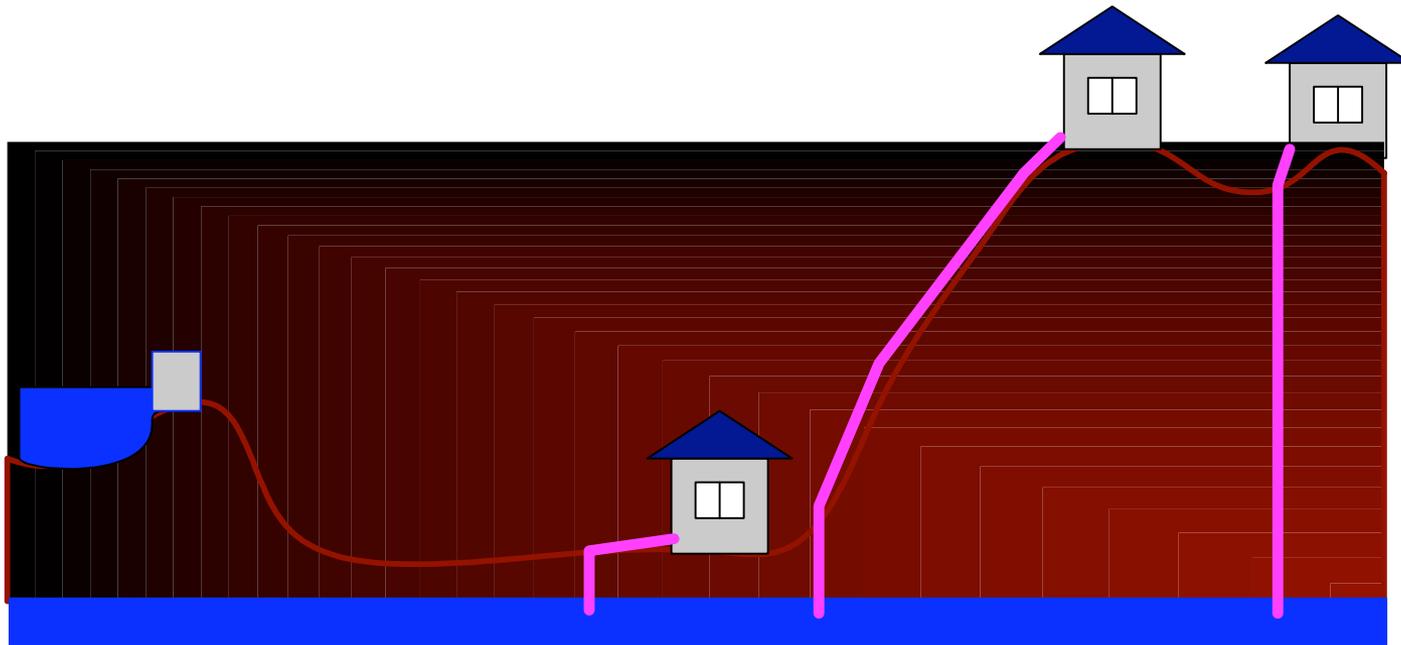


GND Plane



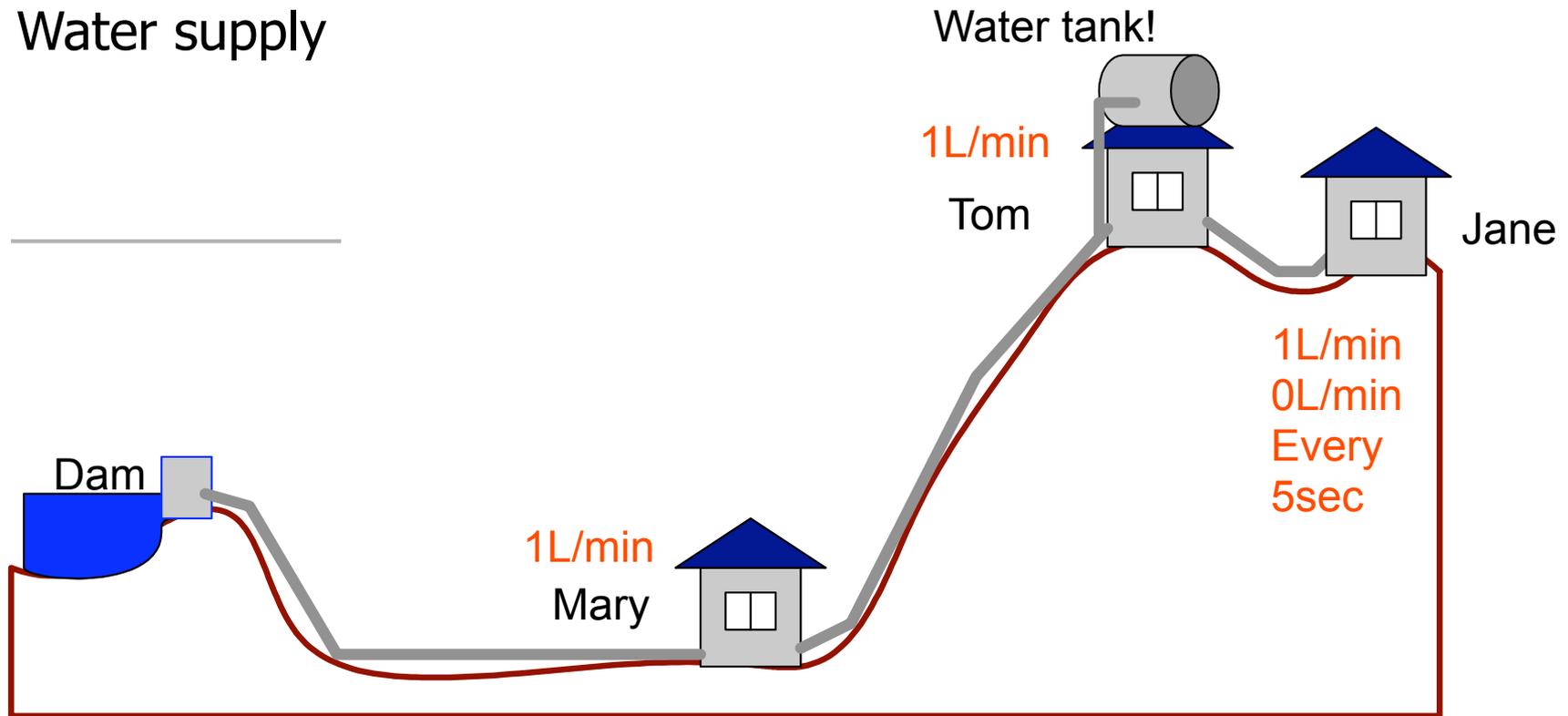
# Solid power planes

- 



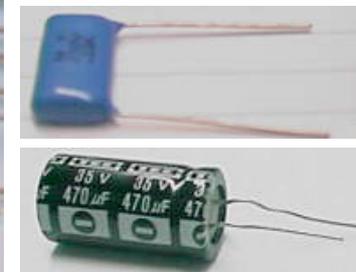
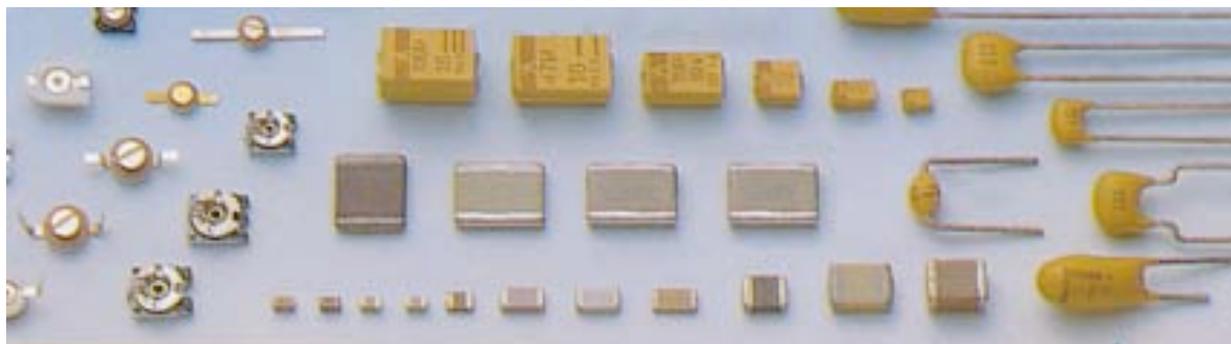
# Bypass capacitor

- Water supply



# Bypass capacitors

- Reduce power supply impedance.
  - Reduce impedance between VCC and GND.
  - Prevent from abrupt current change thus reducing ground bounce.
  - Monolithic and chip capacitors



# Bypass capacitors (contd.)

- For digital systems
  - Low equivalent series inductance (ESL) and low equivalent series resistance (ESR) capacitors.



a) Ideal



b) real condition



# Single sided universal PCB

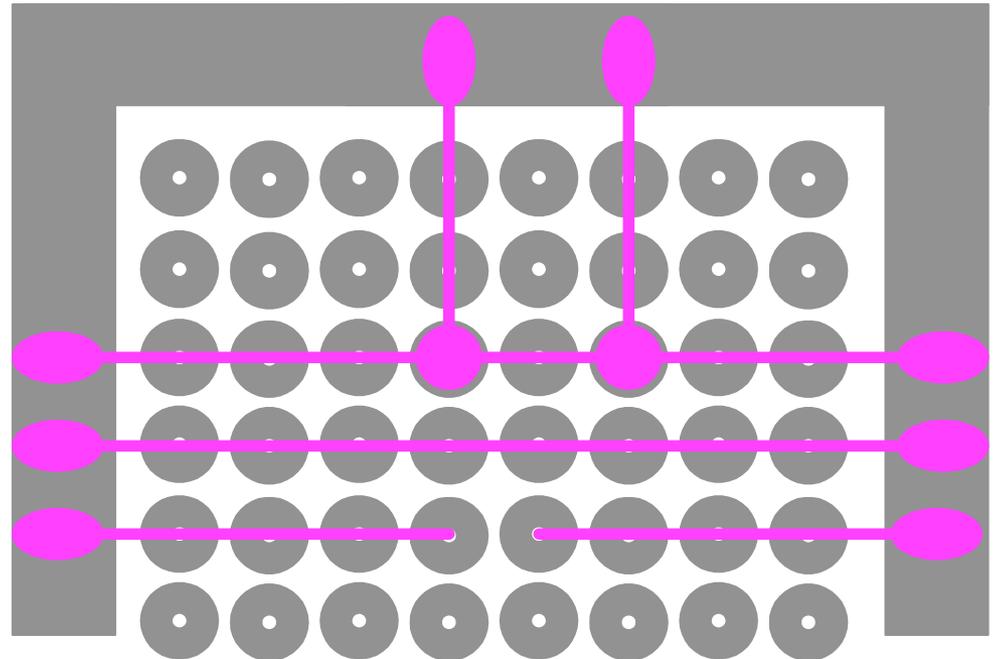
- Use power bus
  - VCC and GND fingers layout
  - As straight as possible
  - Use tin-plated wire
  - Use bypass capacitors
  - RLC, diode and transistor experiments



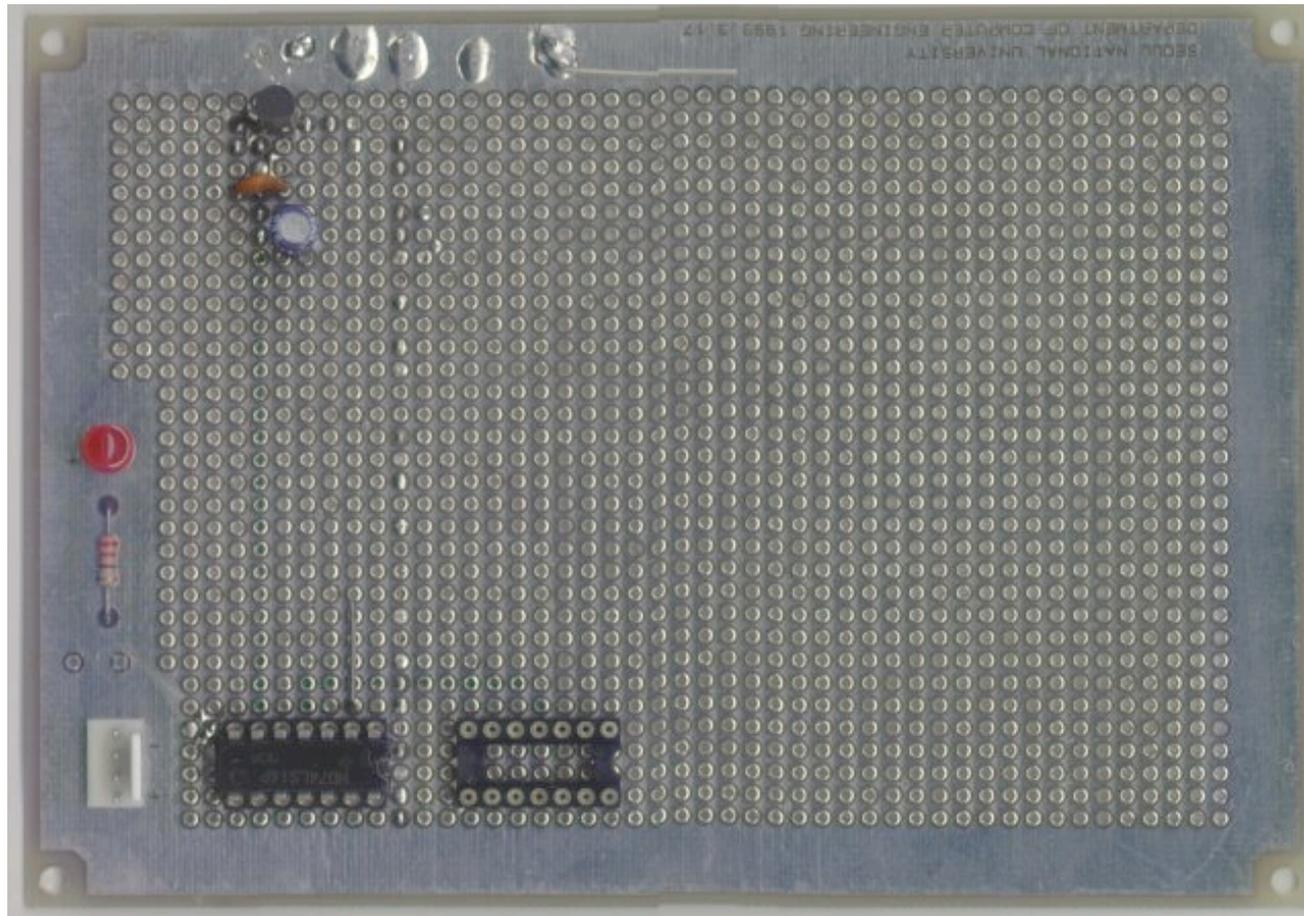


# Double sided solid GND plane universal PCB (contd.)

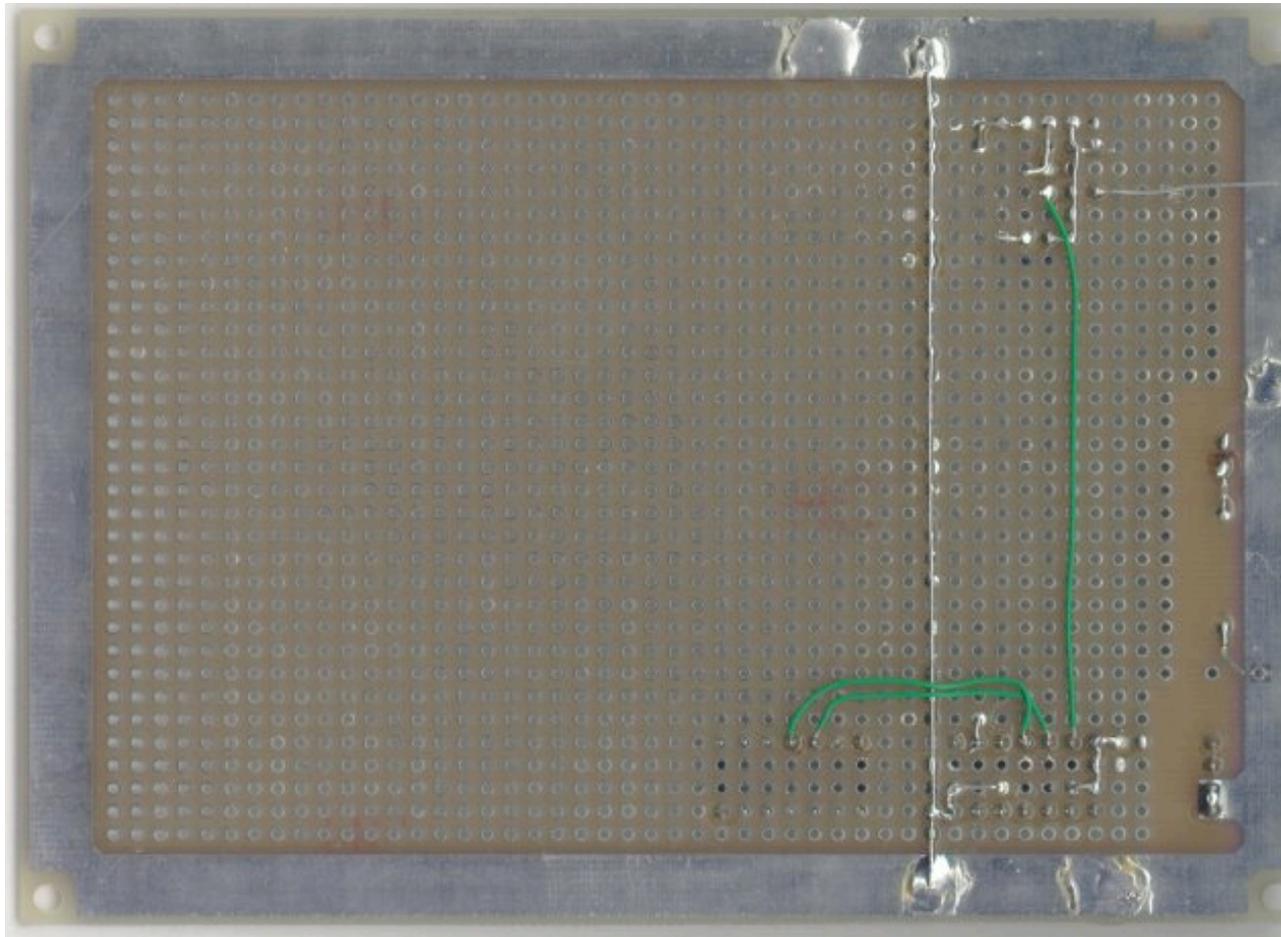
- Make VCC mesh (grid)
  - Still worse than GND
- Use plenty of bypass capacitors
  - Compensate VCC impedance



# SNUCOM board: component side

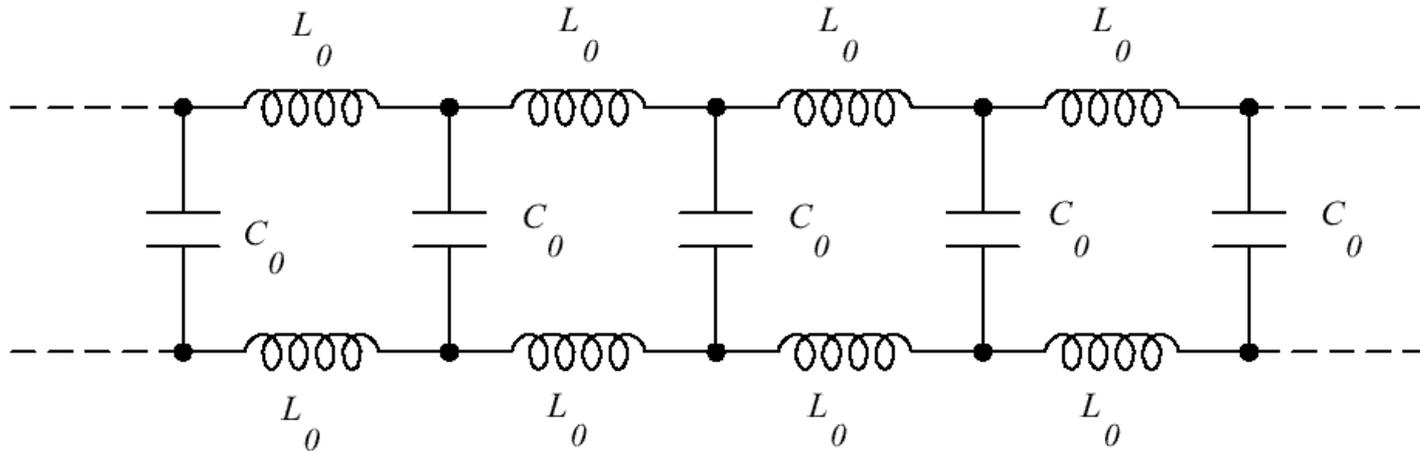


# SNUCOM board: solder side



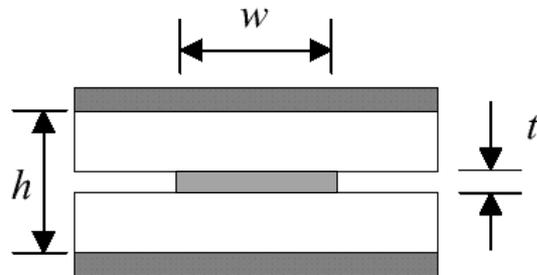
# Controlled impedance line

- Inductance and capacitance are evenly distributed along the length of the line

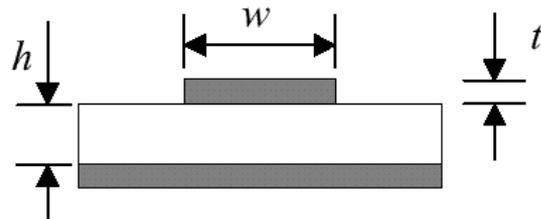


# Controlled impedance line (contd.)

- Stripline and microstripline



Stripline



Microstripline



# Controlled impedance line (contd.)

- Coplanar waveguide
  - Often used in RF circuits
  - Often can be seen with copper pour

